AMENDMENTS TO THE SPECIFICATION

On page 7, line 27 please delete the call out number 34.

On page 7, line 28 please delete the call out number 35.

The new paragraph is shown below.

Preferably the sound emitting means [[34]] comprises an electronic microchip sound generating device [[35]] comprised of a generally flat-shaped speaker 34, a microchip controller 35 mounted to a circuit board 32, a switch means 255, and a battery means 190. (FIG. 2) In such an embodiment, the speaker 34, microchip controller 35, circuit board 32, switch means 255, and battery means 190 are all electronically connected in such a way that upon closing of the switch means 255 a circuit is completed and the predetermined sound is produced by the speaker 34. In one embodiment of the invention, the speaker 34 is mounted to the circuit board 32, while in another embodiment of the invention the speaker 34 is mounted face-down and adjacent to the circuit board 32 against the foldable support structure 120 and is connected to the circuit board 32 with wires 305.

On page 8, line 10 please delete the call out number 35. On page 8, line 16 please delete the call out number 35.

The new paragraph is shown below.

A slide tongue mechanism 38 having a pair of ends 150 is included such that one end 55 thereof is slidably connected to the electronic microchip sound generating device 35 such that sliding of the tongue mechanism 38 generally along one dimension causes either activation or deactivation of the sound generating device [[35]]. The other end 56 of the tongue mechanism 38 is attached to the foldable support structure 120. In one embodiment, the other end 56 of the tongue mechanism 38 includes a tongue attachment means 158 that is fixed at a top side Fig.4, 160 and a bottom side 170 thereof to the foldable support structure 120 with double-sided tape 48 or the like. As such, the folding or unfolding of the foldable support structure 120 causes the tongue mechanism 38 to either deactivate or activate the electronic microchip sound generating device [[35]], respectively.

On page 9, line 21 please delete the call out number 35.

On page 9, line 22 please delete the call out number 35.

The new paragraph is shown below.

The microchip sound generating device [[35]] is held within a generally flat-shaped pocket formed by the folded secondary page 20 in such a way that the microchip sound generating device [[35]] is retained about halfway between the vertical and horizontal midpoint of the secondary page 20 and the outer edge fold line 80 of the secondary page 20.

On page 9, line 17 please delete the call out number 60.

On page 9, line 19 please delete the call out number 75.

The new paragraph is shown below.

The dotted line in figure 3 between the speaker panel 34 and the circuit chip panel above shows that the speaker panel can be overlapping, underlapping or exactly adjacent to the circuit chip panel. Usually, during hand assembly the speaker is not exactly aligned so that the panel interface is flush. Error and misaligned panels are expected and do not diminished the function of the overall device [[60]] as long as the speaker is placed in the approximate required location. In the best mode, the speaker is placed below the circuit chip board at about two-thirds of the page away from the main folding line [[75]].

On page 9, line 28 please delete the call out number 35.

The new paragraph is shown below.

A modular template 60 formed from a sheet of flexible film or other generally flat and durable sheet material may be further included for mounting of the microchip sound generating device [[35]]. The modular template 60 is modular because it has a plurality of modules. Each of the modules can be called a section. It is more efficient to form the sections generally rectangular in

shape. A single modular template 60 can be used for different sized magazines by detaching certain sections from the template allowing changing of the footprint to best suit different sized and different shaped magazines.

On page 10, line 24 please delete the call out number 200.

On page 10, line 27 please delete the call out number 60.

On page 10, line 29 please delete the call out number 60.

The new paragraph is shown below.

The bottom side of the modular template film [[200]] would include a contact adhesive such as sticky tape 270 or the like having a removable liner 280 such that when the liner 280 is removed, the sticky tape 270 is exposed so that the modular template 60 may be quickly and easily fixed to the primary and secondary pages [[60,]] 20. The modular template 60 serves to maintain accurate placement and spacing of the tongue mechanism 38 with respect the two ends 55, 56 thereof, the first page [[60]], and the switch means 255. This facilitates assembly and improves the percentage of operational inserts 110 after assembly thereof.

On page 11, line 3 please delete the call out number 35.

On page 11, line 8 please delete the call out number 35.

On page 11, line 12 please delete the call out number 35.

The new paragraph is shown below.

In use, with the foldable section 30 in a closed and folded position, the tongue mechanism 38 is positioned preferably between two contacts of the switch means 255 of the microchip controller [[35]]. The tongue mechanism 38, at least at its first end 55, is formed from a non-conductive material, and as such, the circuit is not complete and no sound is produced by the sound emitting means 34. However, when the foldable section 30 is moved from its closed and folded position to an open and unfolded position, such that the primary and secondary pages are pulled away from each other, the tongue mechanism 38 is pulled away from between the contacts of the switch means 255 of the microchip controller [[35]], completing the electronic circuit, and cause

the predetermined sound to be produced from the speaker 34. The predetermined sound is produced for a predetermined period of time, after which the microchip controller [[35]] becomes inactive. The sound may be produced again by folding the primary and secondary pages together once more, forcing the tongue mechanism 38 between the contacts of the switch means 255 and thereby resetting the electronic microchip sound generating device [[35]] to its initial condition.

On page 13, line 19 please delete the call out number 34.

While a particular form of the invention has been illustrated and described, it will be apparent that various modifications can be made without departing from the spirit and scope of the invention. For example, the exact placement of the sound emitting means 34 may vary within the pocket formed by folding the secondary page 20. The tape 90 may alternately be a dab of glue. Accordingly, it is not intended that the invention be limited, except as by the appended claims.